

[DETECTING METHOD FOR DRY ETCHING MACHINE]

Abstract

A detecting method for the dry etching machine under the semiconductor process is introduced. A certain number of wafers are sequentially performed with a dry etching process, wherein the V_{pp} value of each wafer under the etching process is recorded. Next, the V_{pp} values are processed by a mathematical algorithm, for eliminating some unreasonable values. Then, a V_{pp} range under the normal operation condition is obtained, based one the prediction from the mathematical algorithm, and is sent to the control system of the dry etching machine. The V_{pp} value of the wafer is compared to the V_{pp} range. If the V_{pp} value is within the V_{pp} range then it indicates a normal operation. If the V_{pp} value is out of the V_{pp} range, then the control system of the etching machine automatically stops the machine and issues a warning signal by voice or by E-mail or pager, so as to inform the operator to adjust the fabrication parameters for dry etching machine.